

Marking and labeling of components, PCBs and PCBAs to identify lead(Pb), Pb-free and other attributes

ICS 31.190

National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

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PUBLICLY AVAILABLE SPECIFICATION

**Marking and labeling of components, PCBs and PCBAs to identify lead(Pb),
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IPC/JEDEC J-STD-609

Marking and Labeling of Components, PCBs and PCBAs to Identify Lead(Pb), Pb-Free and Other Attributes

A joint standard developed by the Marking, Symbols and Labels for Identification of Assemblies, Components and Devices Task Group (4-34b) and JEDEC Committee JC14.4 Quality Processes and Methods

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Users of this publication are encouraged to participate in the development of future revisions.

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